

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>KOHEI MIYAMOTO</td> <td>10/03/2013</td> </tr> <tr> <td>mitsushige HAMAGUCHI</td> <td>10/03/2013</td> </tr> <tr> <td>HIDEYUKI UMETSU</td> <td>10/03/2013</td> </tr> </tbody> </table>		Name	Execution Date	KOHEI MIYAMOTO	10/03/2013	mitsushige HAMAGUCHI	10/03/2013	HIDEYUKI UMETSU	10/03/2013		
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CORRESPONDENCE DATA											
<p>Fax Number: (215)656-2498</p> <p>Email: pto.phil@dlapiper.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: IP GROUP OF DLA PIPER LLP</p> <p>Address Line 1: 1650 MARKET STREET, SUITE 4900</p> <p>Address Line 4: PHILADELPHIA, PENNSYLVANIA 19103</p>											
ATTORNEY DOCKET NUMBER:	MIP-13-1383										
NAME OF SUBMITTER:	T. DANIEL CHRISTENBURY										
Signature:	/TDC/										

Date:

02/03/2014

Total Attachments: 2

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COMBINED DECLARATION/ASSIGNMENT

WHEREAS, we

Kohei MIYAMOTO of Aichi, Japan  
Mitsushige HAMAGUCHI of Aichi, Japan  
Hideyuki UMETSU of Aichi, Japan

(hereinafter referred to as "the undersigned"), have made an invention entitled THERMOPLASTIC RESIN COMPOSITION AND ITS MOLDED PRODUCT, identified in International Application No. PCT/JP2012/007615, and US Application No. 14/236,232, (DLA Piper is authorized to insert the Serial No. when known),

the above-identified application was made or authorized to be made by the persons executing this Declaration;

we believe that we are the original joint inventors of a claimed invention in the application;

we hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 USC §1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, TORAY Industries, Inc., with offices at 1-1, Nihonbashi-Muromachi 2-chome, Chuo-ku, Tokyo 103-8666, Japan, (hereinafter referred to as "assignee"), are desirous of acquiring the entire right, title and interest in said invention, said US application and all letters patent issuing for said invention,

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and of other good and valuable consideration, receipt of which is hereby acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignees the entire right, title and interest, for the United States of America, its territories and possessions, and for all foreign countries, in said invention, including said US application, all divisions and continuations thereof, all rights to claim priority based thereon, all rights to file foreign applications on said invention, and all letters patent and reissues thereof, issuing for said invention in the United States of America and in any and all foreign countries.

It is agreed that the undersigned shall be legally bound, upon request of the assignees, or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the undersigned has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the assignee, and to execute all instruments proper to carry out the intent of this instrument. If

the undersigned includes more than one individual, these obligations shall apply to all of the undersigned both individually and collectively.

The rights and property herein conveyed by the undersigned are free and clear of any encumbrance.

EXECUTED on the dates set forth below.

October 3, 2013  
Date

October 3, 2013  
Date

October 3, 2013  
Date

Kohei Miyamoto  
Kohei MIYAMOTO

Mitsushige Hamaguchi  
Mitsushige HAMAGUCHI

Hideyuki Umetsu  
Hideyuki UMETSU